

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE6050IA uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

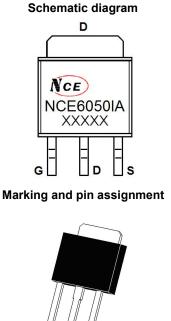
- V_{DS} =60V,I_D =50A
 R_{DS(ON)} <14mΩ @ V_{GS}=10V
 R_{DS(ON)} <19mΩ @ V_{GS}=4.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



(2) D

(3) s

(1) GO

TO-251 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6050IA	NCE6050IA	TO-251	-	-	-

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	ID	50	А
Drain Current-Continuous(Tc=100 ℃)	I _D (100℃)	35.4	А
Pulsed Drain Current	I _{DM}	200	А
Maximum Power Dissipation	PD	85	W
Derating factor		0.56	W/℃
Single pulse avalanche energy (Note 5)	Eas	300	mJ
Operating Junction and Storage Temperature Range	TJ,TSTG	-55 To 175	°C



Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{ejc}	1.8	°C/W	
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Electrical Characteristics (Tc=25°C unless otherwise noted)

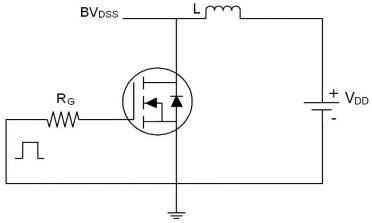
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	60	-	-	V
Zero Gate Voltage Drain Current	IDSS	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	lgss	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.0	-	2.0	V
Drain-Source On-State Resistance		V _{GS} =10V, I _D =20A	-	12	14	mΩ
	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A	-	16	19	mΩ
Forward Transconductance	G FS	V _{DS} =5V,I _D =20A	18	-	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	Clss		-	1630	-	PF
Output Capacitance	Coss	- V _{DS} =30V,V _{GS} =0V, - F=1.0MHz	-	113	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHZ	-	97	-	PF
Switching Characteristics (Note 4)	I					
Turn-on Delay Time	t _{d(on)}		-	7.4	-	nS
Turn-on Rise Time	tr	V _{DD} =30V, R∟=6.7Ω	-	5.1	-	nS
Turn-Off Delay Time	t _{d(off)}		-	28.2	-	nS
Turn-Off Fall Time	t _f		-	5.5	-	nS
Total Gate Charge	Qg	N/ 001/1 004	-	39		nC
Gate-Source Charge	Qgs		-	7		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	8.5		nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	Vsd	V _{GS} =0V,I _S =20A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	50	A
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =20A	-	28	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	40	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negl	igible (tur	n-on is do	ominated b	y LS+LD)

Notes:

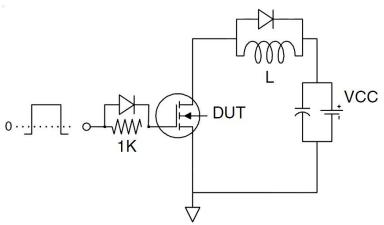
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^\circ \!\! \mathbb{C}$,VDD=30V,VG=10V,L=0.5mH,Rg=25 $\!\Omega$



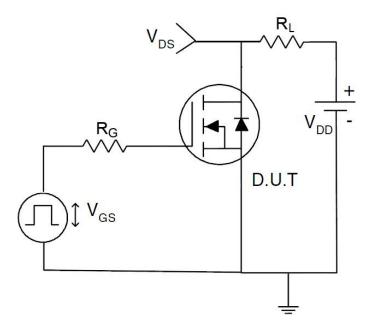
Test Circuit 1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





125

30

25℃

0.6

0.8

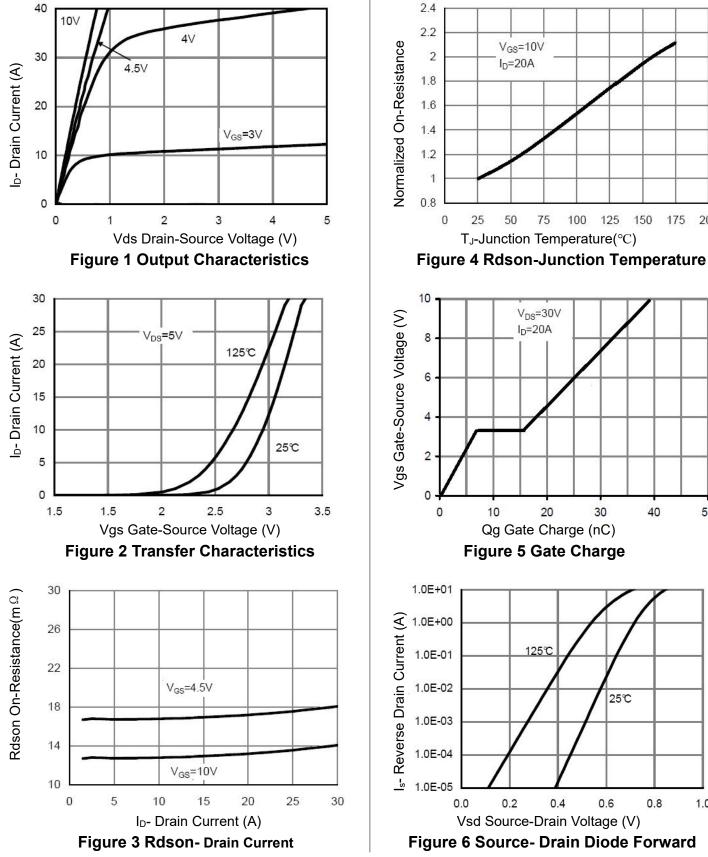
40

50

150 175

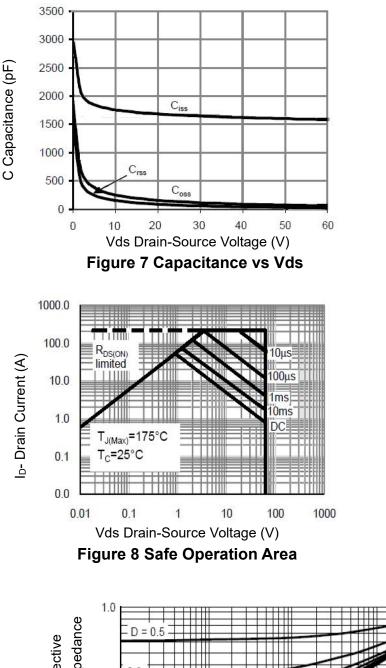
200





1.0





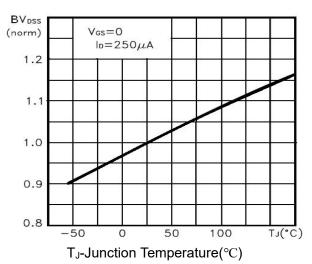


Figure 9 BV_{DSS} vs Junction Temperature

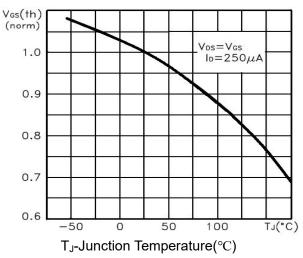
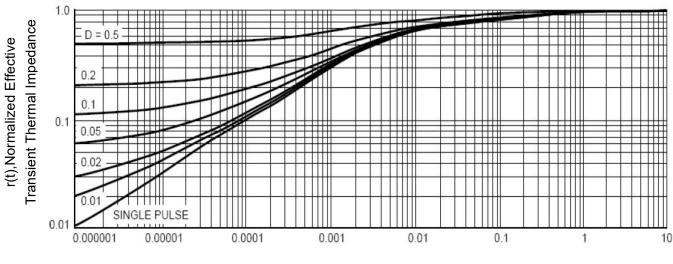


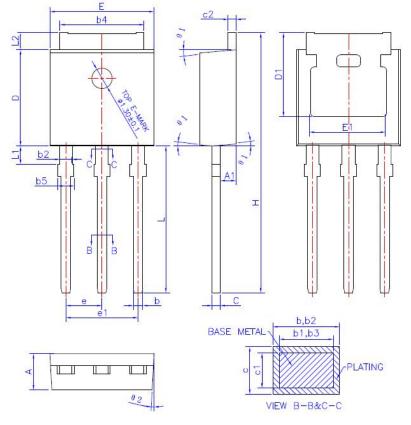
Figure 10 V_{GS(th)} vs Junction Temperature



Square Wave Pluse Duration (sec) Figure 11 Normalized Maximum Transient Thermal Impedance



TO-251 Package Information



COMMON DIMENSIONS (UNITS OF MEASURE =MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	2,20	2,30	2,35
A1	0,90	1,01	1,10
b	0,56	and the second s	0,69
b1	0,55	0,60	0,65
b2	0.77	-	0,90
b3	0.76	0.81	0,86
b4	5,23	5,33	5,43
b5		<u></u>	1,05
С	0.46		0,59
c1	0.45	0.51	0,55
c2	0.46		0,59
D	6.00	6.10	6,20
D1	5.20	1.000	
E	6,50	6.60	6,70
E1	4.60	4.83	5,00
e	2.24	2.29	2.34
e1	4.47	4.57	4.67
H	16.18	16.48	16.78
L	9.00	9.30	9,60
L1	0.95	1.16	1.35
L2	0.90	1.08	1,25
θ1	3°	5°	7°
θ2	1°	3°	5°



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